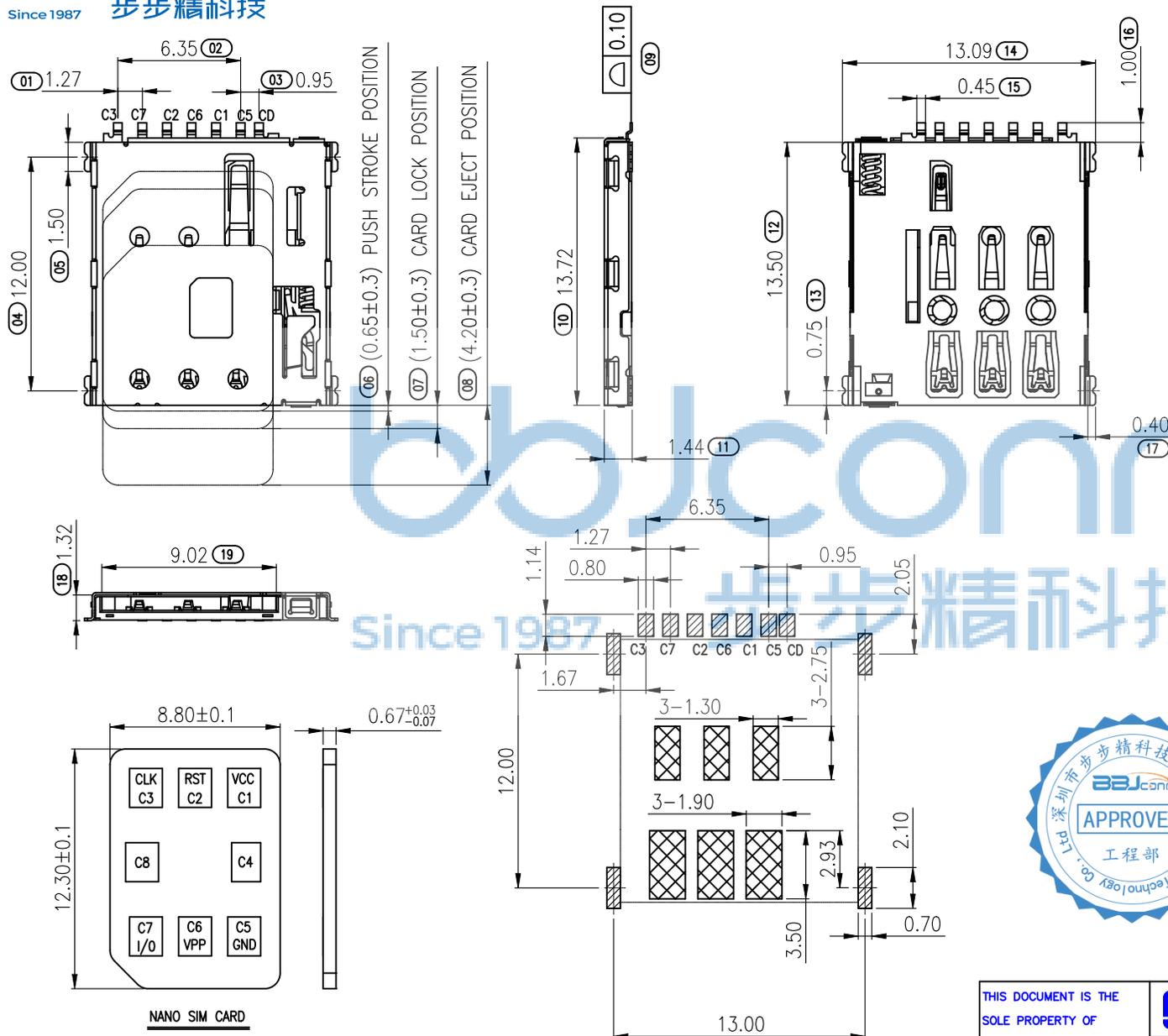


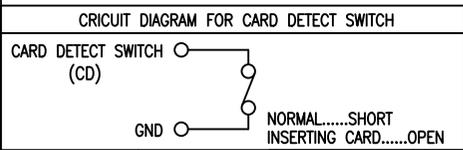
REV.	ECN NO	CONTENT	DATE	ENGINEER
AO				

NOTES:

- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT:COPPER ALLOY
SHELL:STAINLESS STEEL
- PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
- SPECIALITY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:50mΩ MAX
3.4 Insulation Resistance:1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:260+0/-5°C, 30±10s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition:Temperature-40°C~+85°C
Humidity 80% R.H MAX



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



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PDWG.NO: 0302-1

深圳市步步精科技有限公司

NAME: 卡座 NANO SIM CARD PUSH 7PIN 带CD PIN H=1.37 贴片 无铅 自弹(C-102314452-00)

APPD. JM_Zheng

CHKD. LYX

DR. TSP

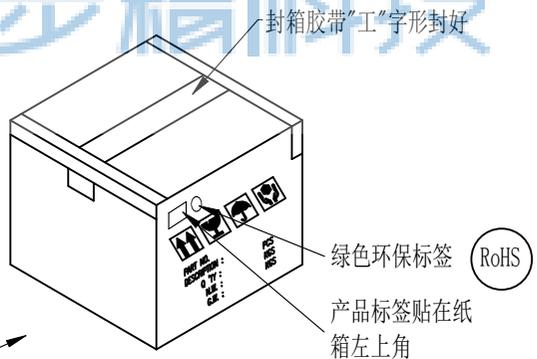
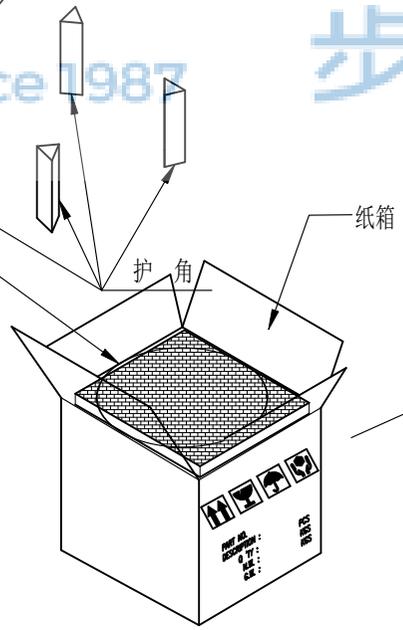
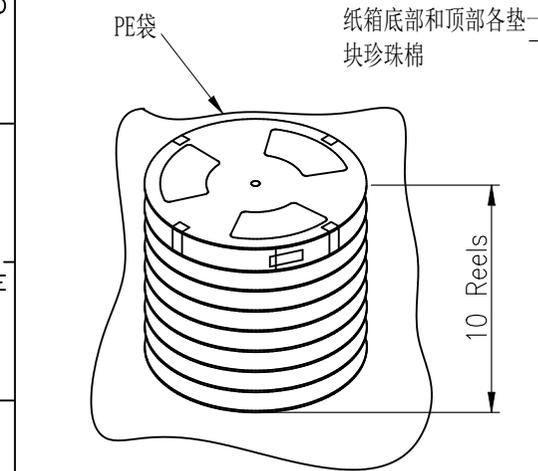
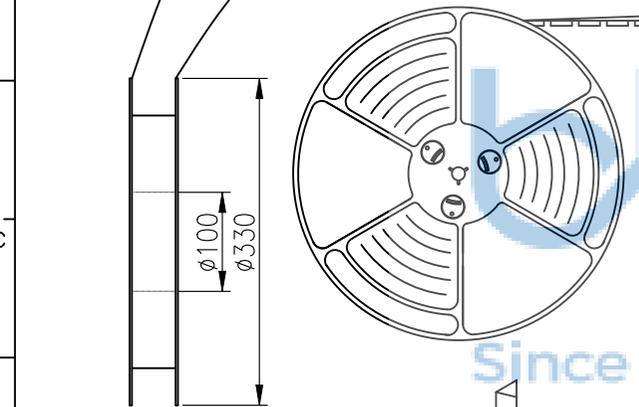
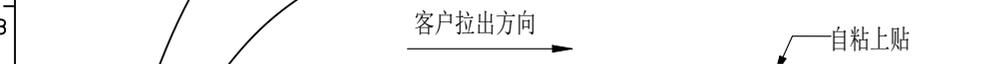
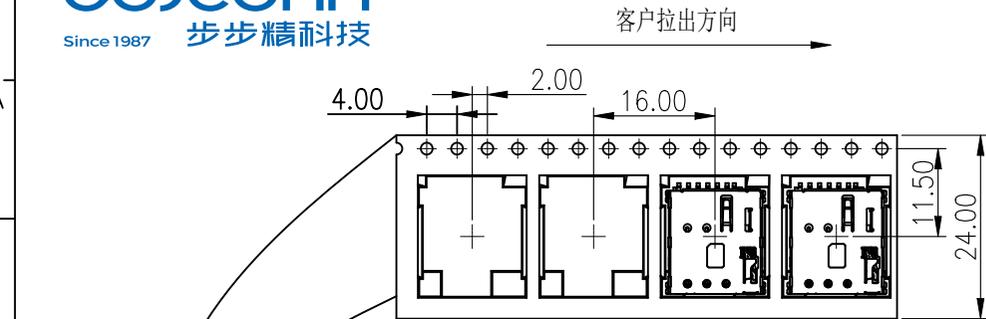
PJ. NO.: 142-216-070001-V8G

SIZE: A4 DRW NO.:

FINISH: SEE NOTES MAT'L.: SEE NOTES

SCALE: N/A REV.: AO UNIT: mm PAGE: 1/2

REV.	ECN NO	CONTENT	DATE	ENGINEER
AO				



NOTES

1. 每卷包装数量:1500PCS/每卷
2. 卷带包装方式:
3. 每箱包装数量:15000PCS/箱
4. 纸箱350mm*350mm*340mm(内部尺寸), 材质K=K



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PDWG.NO: 0302-1	DR. TSP	APPD. JM_Zheng	CHKD. LYX
.X: ± 0.38 .XX: ± 0.25 .XXX: ± 0.13 X': $\pm 3'$ X'': $\pm 2'$ XX': $\pm 1'$		PJ. NO.: 142-216-070001-V8G SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: AO UNIT: mm PAGE: 2/2	

将10卷产品放入箱内